

# HD74LS37

## Quadruple 2-input Positive NAND Buffers

REJ03D0406-0200  
 Rev.2.00  
 Feb.18.2005

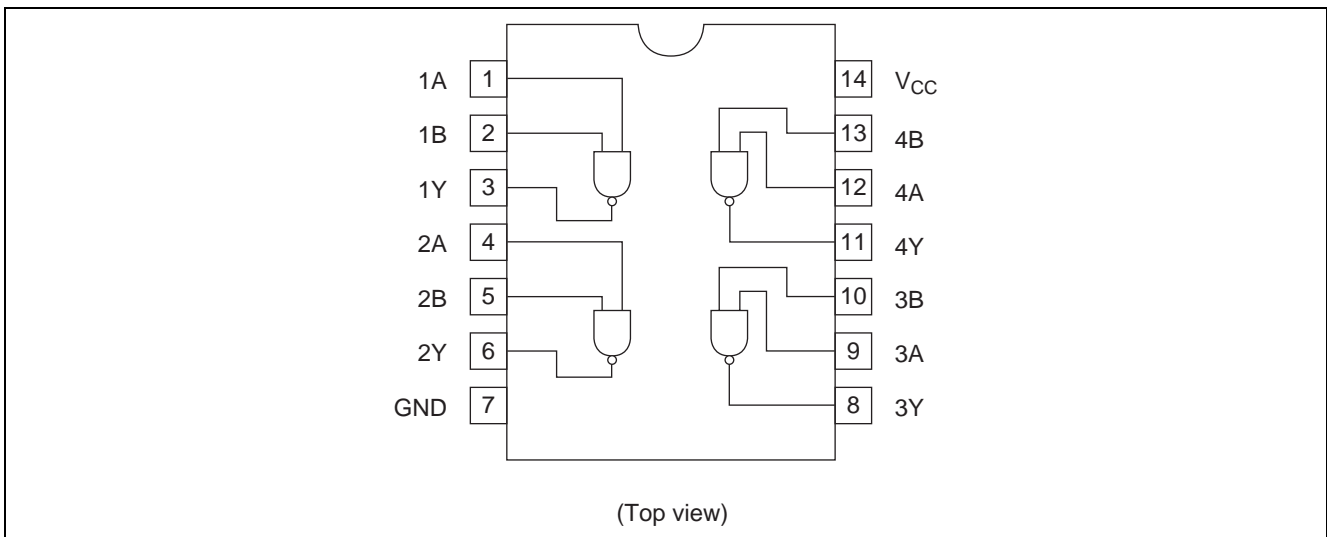
### Features

- Ordering Information

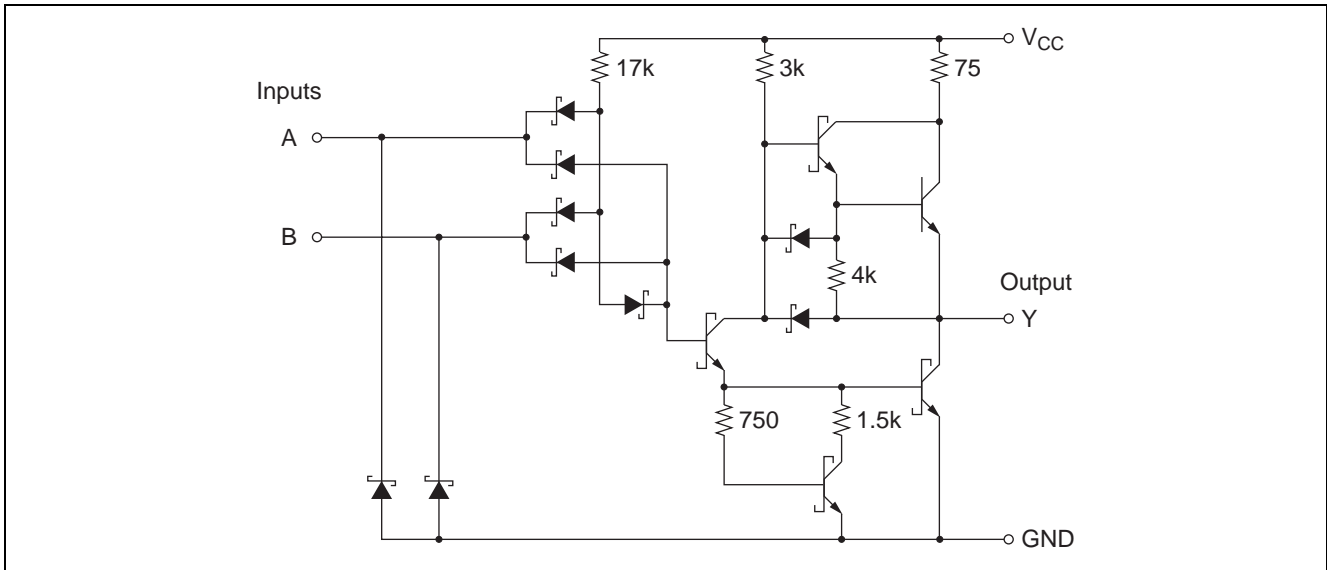
Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS37P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS37FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

### Pin Arrangement



Circuit Schematic (1/4)



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	$V_{CC}$	7	V
Input voltage	$V_{IN}$	7	V
Power dissipation	$P_T$	400	mW
Storage temperature	$T_{stg}$	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	$V_{CC}$	4.75	5.00	5.25	V
Output current	$I_{OH}$	—	—	-1.2	mA
	$I_{OL}$	—	—	24	mA
Operating temperature	$T_{opr}$	-20	25	75	°C

**Electrical Characteristics**

(Ta = -20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V <sub>IH</sub>	2.0	—	—	V	
	V <sub>IL</sub>	—	—	0.8	V	
Output voltage	V <sub>OH</sub>	2.7	—	—	V	V <sub>CC</sub> = 4.75 V, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -1.2 mA
	V <sub>OL</sub>	—	—	0.5	V	I <sub>OL</sub> = 24 mA
		—	—	0.4		I <sub>OL</sub> = 12 mA
Input current	I <sub>IH</sub>	—	—	20	μA	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = 2.7 V
	I <sub>IL</sub>	—	—	-0.4	mA	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = 0.4 V
	I <sub>I</sub>	—	—	0.1	mA	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = 7 V
Short-circuit output current	I <sub>OS</sub>	-30	—	-130	mA	V <sub>CC</sub> = 5.25 V
Supply current	I <sub>CCH</sub>	—	0.9	2.0	mA	V <sub>CC</sub> = 5.25 V
	I <sub>CCL</sub>	—	6	12	mA	V <sub>CC</sub> = 5.25 V
Input clamp voltage	V <sub>IK</sub>	—	—	-1.5	V	V <sub>CC</sub> = 4.75 V, I <sub>IN</sub> = -18 mA

Note: \* V<sub>CC</sub> = 5 V, Ta = 25°C

**Switching Characteristics**

(V<sub>CC</sub> = 5 V, Ta = 25°C)

Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	t <sub>PLH</sub>	—	12	24	ns	C <sub>L</sub> = 45 pF, R <sub>L</sub> = 667 Ω
	t <sub>PHL</sub>	—	12	24	ns	

Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

Package Dimensions



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